

## Features

- ✧ Glass passivated junction chip.
- ✧ For surface mounted application
- ✧ Low forward voltage drop
- ✧ Low profile package
- ✧ Built-in strain relief, ideal for automatic placement
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering:  
260°C/10 seconds at terminals
- ✧ Plastic material used carries Underwriters  
Laboratory Classification 94V-0
- ✧ Meet MSL level 1, per J-STD-020D,  
lead free maximum peak of 260°C
- ✧ Green compound with suffix "G" on packing  
code & prefix "G" on datecode



## Mechanical Data

- ✧ Case: Molded plastic
- ✧ Terminal: Pure tin plated, lead free
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape per EIA STD RS-481
- ✧ Weight: 0.064 grams

## Ordering Information (example)

Part No.	Package	Packing	Packing code	Packing code (Green)
BYG20D	SMA	1.8K / 7" REEL	R3	R3G

## Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbol	BYG20D	BYG20G	BYG20J	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	200	400	600	V
Maximum RMS Voltage	$V_{RMS}$	140	280	420	V
Maximum DC Blocking Voltage	$V_{DC}$	200	400	600	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.5			A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	30			A
Maximum Instantaneous Forward Voltage (Note 1) @ 1.0 A @ 1.5 A	$V_F$	1.3 1.4			V
Maximum Reverse Current @ Rated VR $T_A=25\text{ }^{\circ}\text{C}$ $T_A=100\text{ }^{\circ}\text{C}$	$I_R$	1 10			uA
Pulse energy in avalanche mode, non repetitive (Inductive load switch off) $T_A=25\text{ }^{\circ}\text{C}$ , L=120mH	$E_{RSM}$	20			mJ
Maximum Reverse Recovery Time (Note 2)	$T_{rr}$	75			nS
Typical Thermal Resistance	$R_{\theta JA}$	100			$^{\circ}\text{C/W}$
Operating Temperature Range	$T_J$	- 55 to + 150			$^{\circ}\text{C}$
Storage Temperature Range	$T_{STG}$	- 55 to + 150			$^{\circ}\text{C}$

Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

Note 2: Reverse Recovery Test Conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$

## RATINGS AND CHARACTERISTIC CURVES (BYG20D THRU BYG20J)

FIG.1 FORWARD CURRENT DERATING CURVE

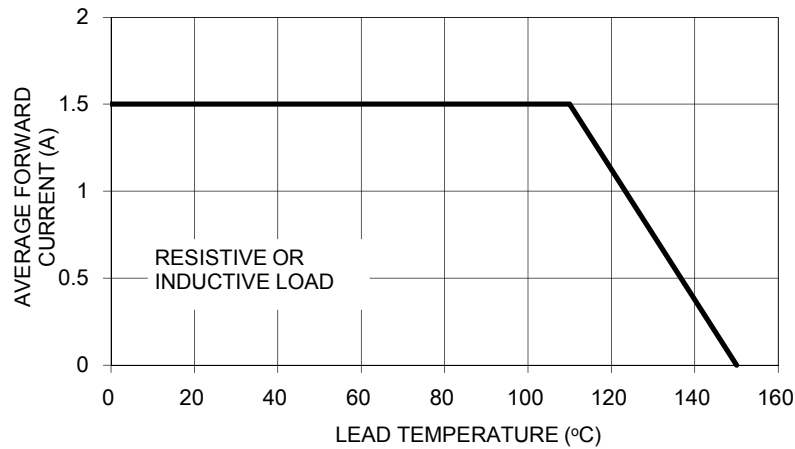


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

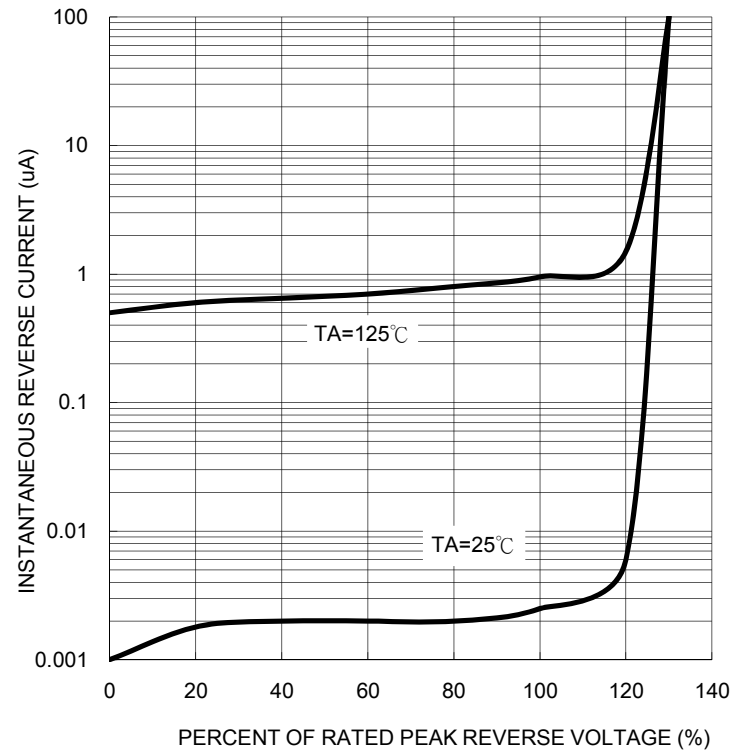


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

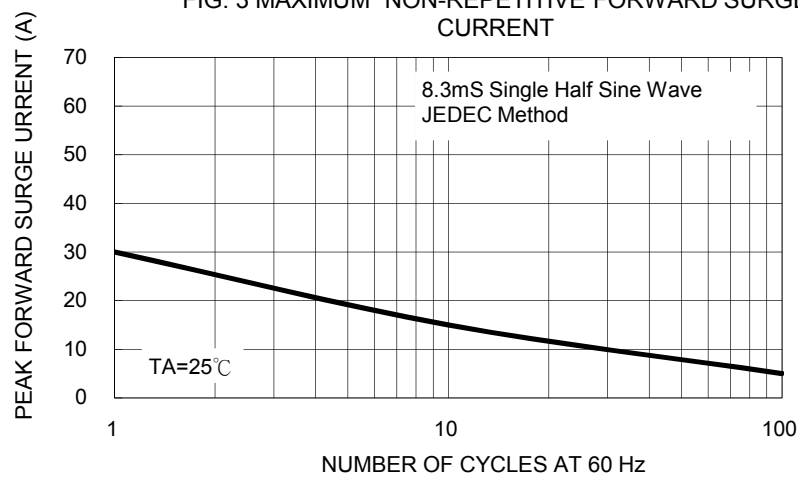


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

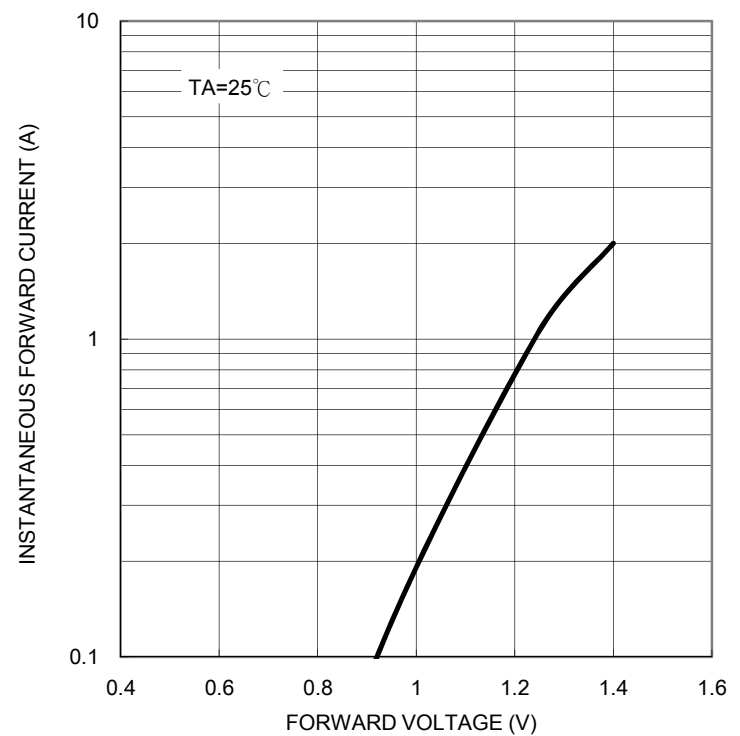


FIG. 4 TYPICAL JUNCTION CAPACITANCE

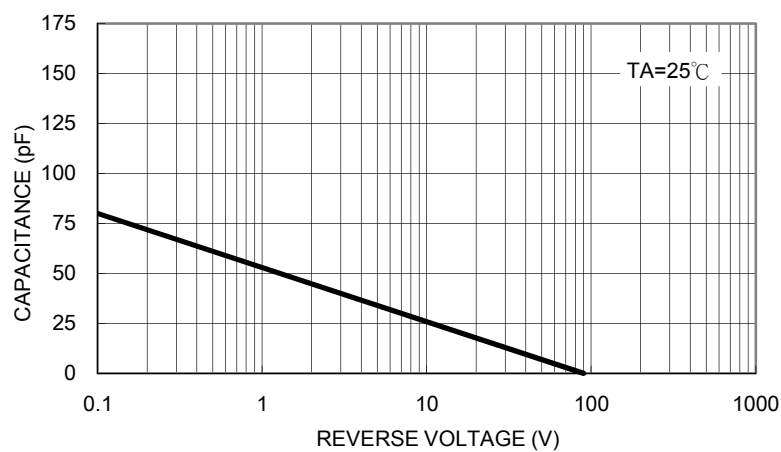
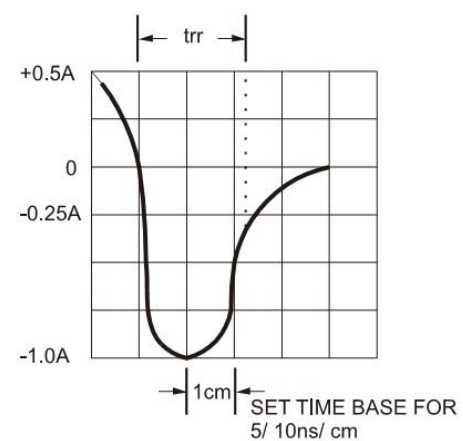
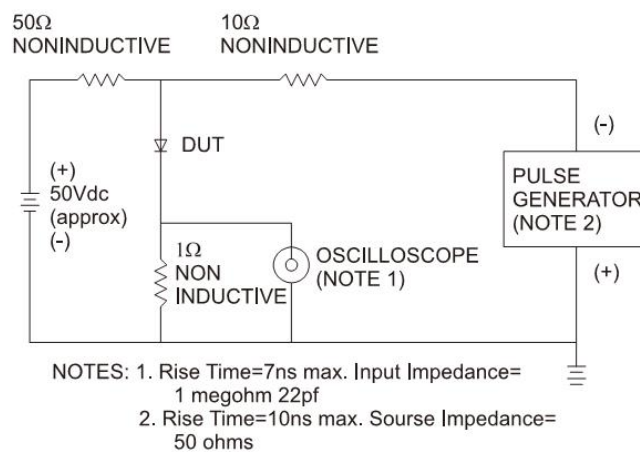


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

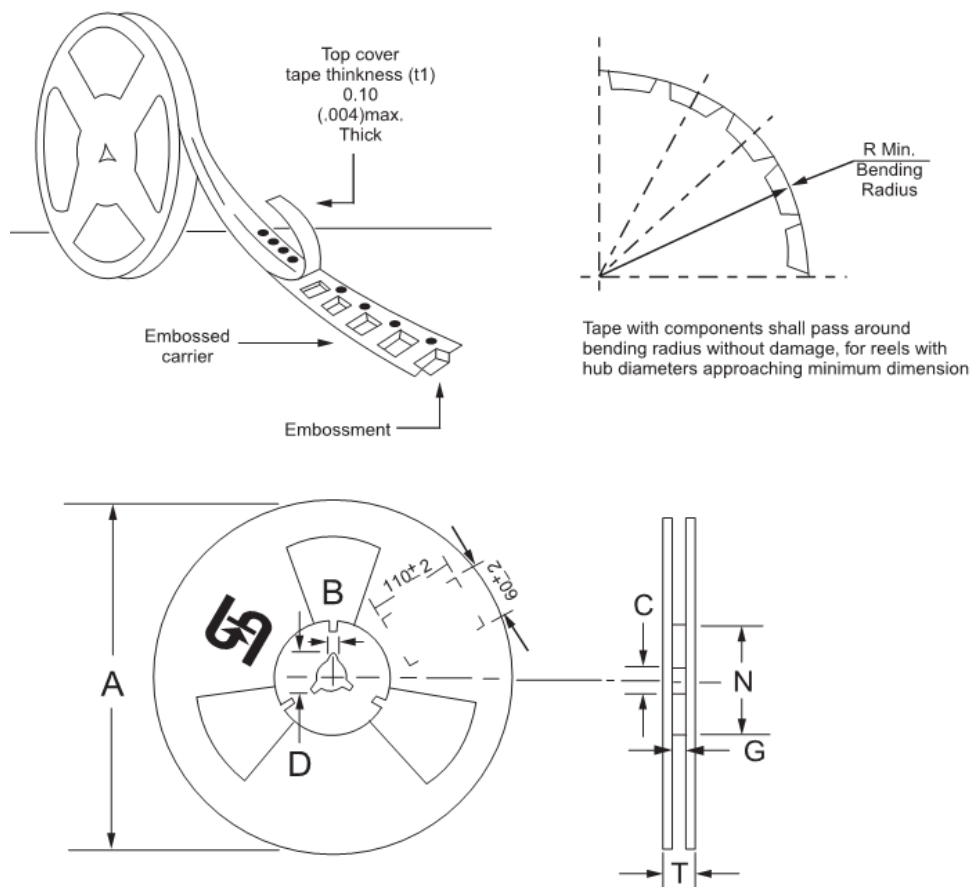


### Ordering information

Part No.	Package	Packing	Packing code	Packing code (Green)
BYG20x (Note)	SMA	1.8K / 7" REEL	R3	R3G
	SMA	7.5K / 13" REEL	R2	R2G
	SMA	7.5K / 13" Plastic REEL	M2	M2G
	Folded SMA	1.8K / 7" REEL	F3	F3G
	Folded SMA	7.5K / 13" REEL	F2	F2G
	Folded SMA	7.5K / 13" Plastic REEL	F4	F4G
	C SMA	1.8K / 7" REEL	E3	E3G
	C SMA	7.5K / 13" REEL	E2	E2G

Note: "x" is Device Code from "D" thru "J".

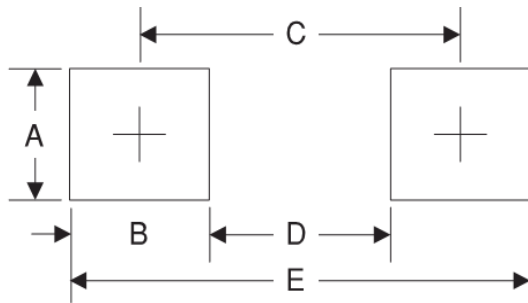
### Tape & Reel specification



Reel Size	Tape Size	A	B	C	D	N	G	T
		±2.0	±0.4	+0.5;-0.2	min	±1.0	+0.8;-0	max
7"	12mm	178	1.9	13	21	62	12.2	14.6
Reel Size	Tape Size	A	B	C	D	N	G	T
		max	±0.5	±0.5	min	±0.5	+2.0;-0	max
13"	12mm	330	2	13	20.2	75	12.4	18.4

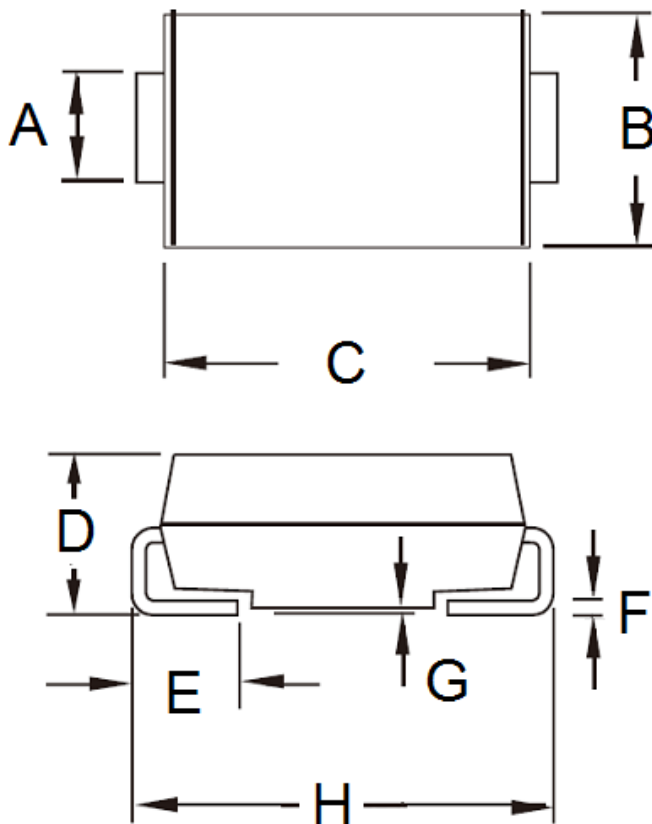
Unit (mm)

### Suggested PAD Layout



Symbol	Unit(mm)
A	1.78
B	1.51
C	3.92
D	2.41
E	4.43

### Package Outline Dimensions



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	1.27	1.58	0.050	0.062
B	2.29	2.83	0.090	0.111
C	4.06	4.60	0.160	0.181
D	1.99	2.50	0.078	0.098
E	0.90	1.41	0.035	0.056
F	0.15	0.31	0.006	0.012
G	0.10	0.20	0.004	0.008
H	4.95	5.33	0.195	0.210

### Marking Diagram



P/N = Specific Device Code  
G = Green Compound  
YW = Date Code  
F = Factory Code

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[BYG20J](#) [BYG20D](#) [BYG20G](#)